

REMARKS

The specification has been amended to correct errors of a typographical and grammatical nature. Due to the large number of corrections thereto, applicants submit herewith a Substitute Specification, along with a marked-up copy of the original specification for the Examiner's convenience. Applicants submit that the substitute specification includes no new matter. Therefore, entry of the Substitute Specification is respectfully requested.

The claims have been amended to cancel original claims 9-19.

The abstract has also been amended to more clearly describe the features of the present invention.

Entry of the preliminary amendments and examination of the application is respectfully requested.

To the extent necessary, applicant's petition for an extension of time under 37 CFR 1.136. Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 01-2135 (501.43736X00) and please credit any excess fees to such deposit account.

Respectfully submitted,



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ABSTRACT

A semiconductor device has an improved mounting reliability and has external terminals formed by exposing portions of leads from a back surface of a resin sealing member. End portions on one side of the leads are fixed to a back surface of a
5 semiconductor chip, and portions of the leads positioned outside the semiconductor chip are connected with electrodes formed on the semiconductor chip through wires.